

Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

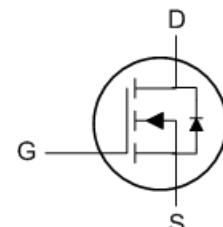
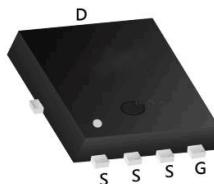
Product Summary

BVDSS	RDS(ON)	ID
100V	7mΩ	82A

DFN5X6 Pin Configuration

Applications

- High Frequency Switching and Synchronous Rectification.
- DC/DC Converters.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	82	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	52	A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	12.8	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	10.3	A
I _{DM}	Pulsed Drain Current ²	250	A
EAS	Single Pulse Avalanche Energy ³	186	mJ
I _{AS}	Avalanche Current	61	A
P _D @T _C =25°C	Total Power Dissipation ⁴	83	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1.5	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	5.6	7	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=20\text{A}$	---	7.3	9	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.2	1.7	2.3	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.5	---	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=20\text{A}$	---	23.8	---	nC
Q_{gs}	Gate-Source Charge		---	6.5	---	
Q_{gd}	Gate-Drain Charge		---	10.7	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3\Omega$, $I_D=20\text{A}$	---	8.5	---	ns
T_r	Rise Time		---	5	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	30	---	
T_f	Fall Time		---	4.5	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2377	---	pF
C_{oss}	Output Capacitance		---	409	---	
C_{rss}	Reverse Transfer Capacitance		---	5	---	

Diode Characteristics

I_s	Continuous Source Current ^{1,5}	$V_{\text{G}}=V_{\text{D}}=0\text{V}$, Force Current	---	---	82	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=61\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_s , in real applications , should be limited by total power dissipation.

Typical Characteristics

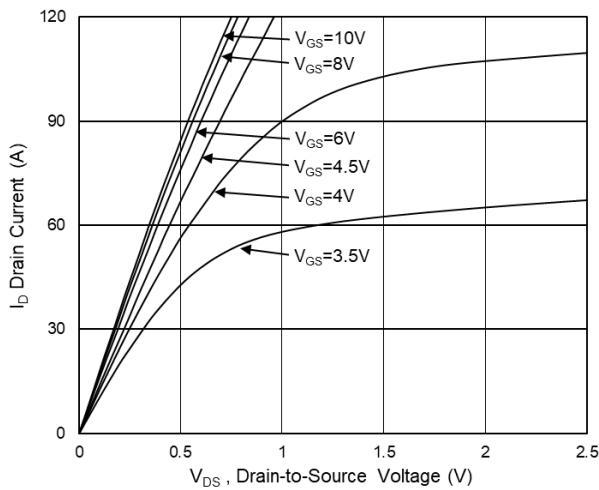


Fig.1 Typical Output Characteristics

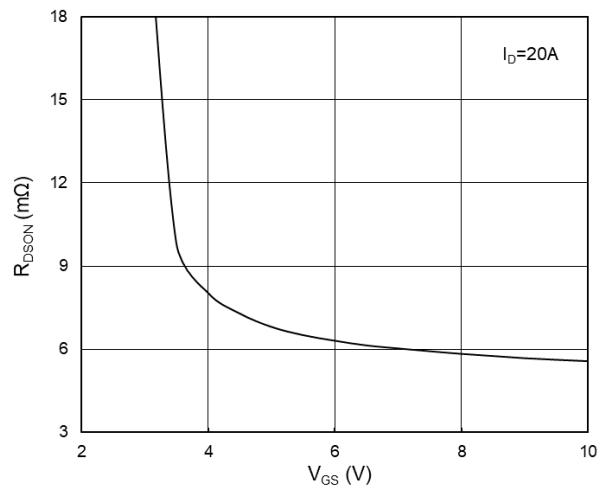


Fig.2 On-Resistance vs G-S Voltage

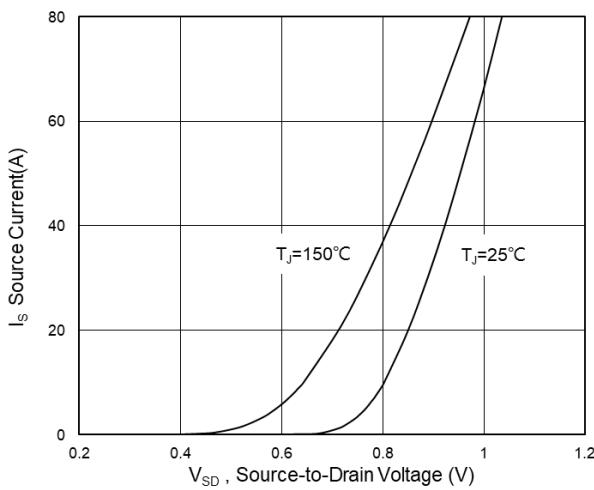


Fig.3 Source Drain Forward Characteristics

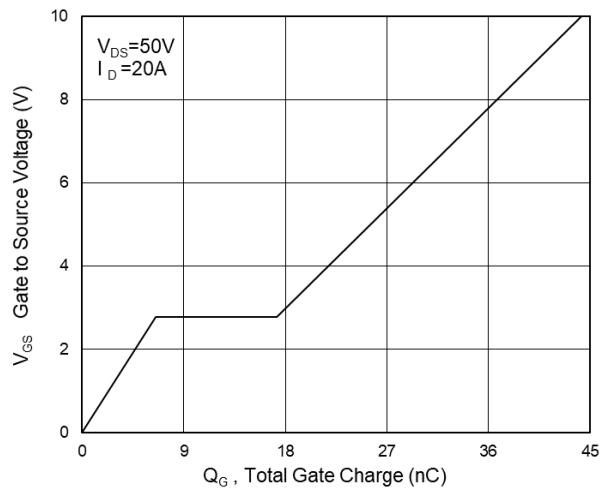


Fig.4 Gate-Charge Characteristics

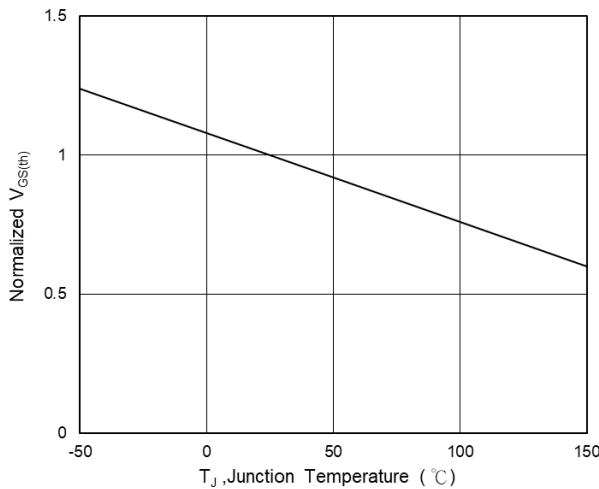


Fig.5 Normalized $V_{GS(th)}$ vs T_J

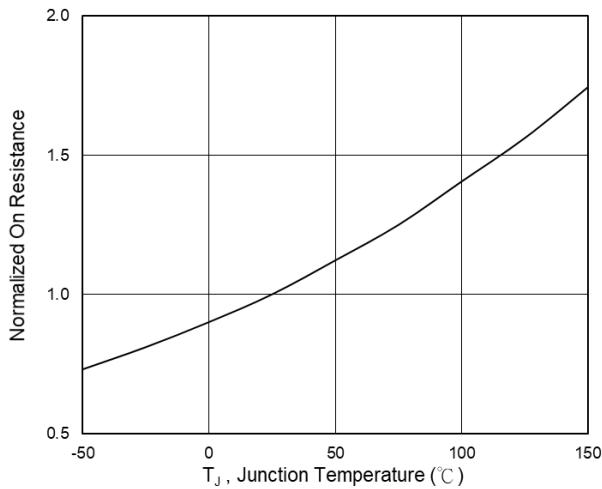


Fig.6 Normalized $R_{DS(on)}$ vs T_J

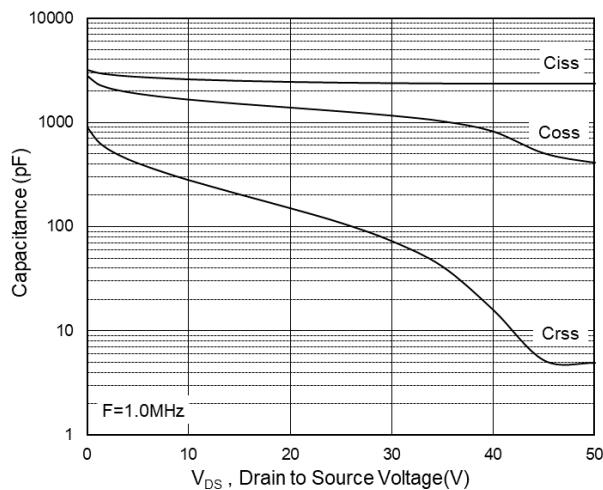


Fig.7 Capacitance

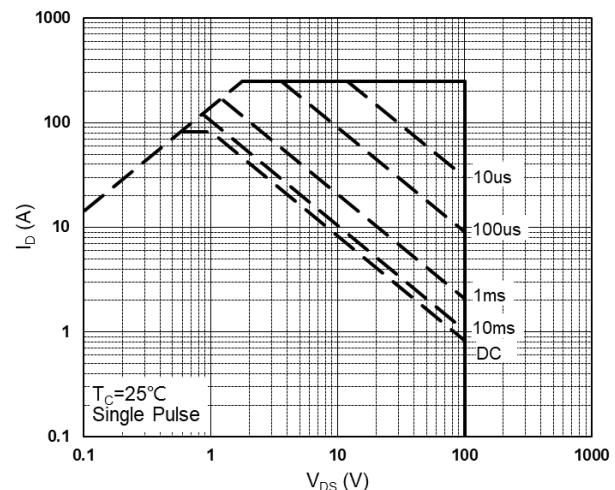


Fig.8 Safe Operating Area

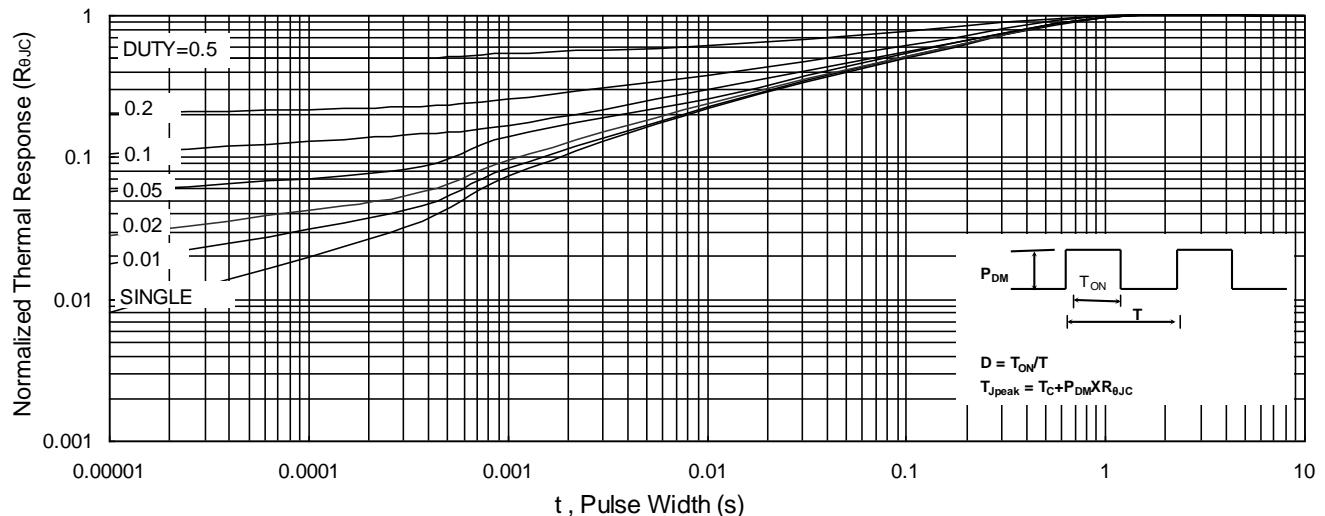


Fig.9 Normalized Maximum Transient Thermal Impedance

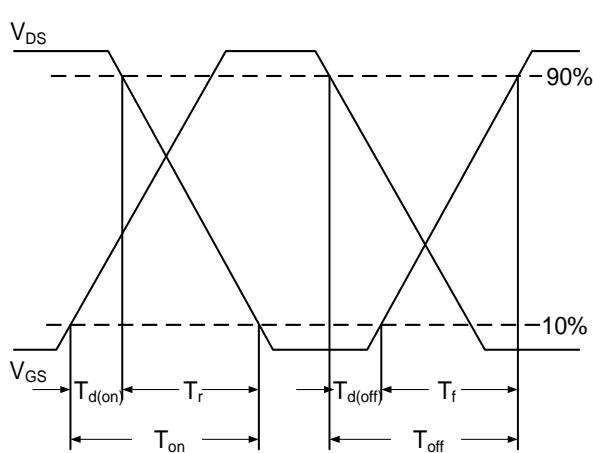


Fig.10 Switching Time Waveform

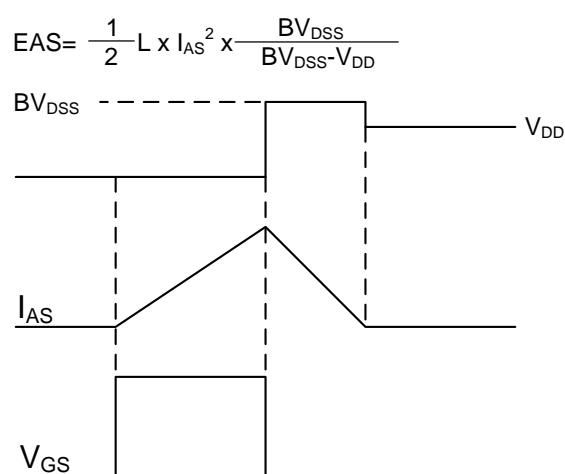
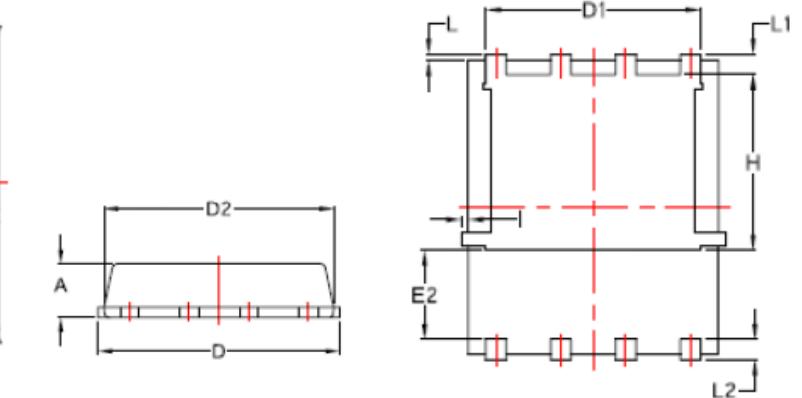
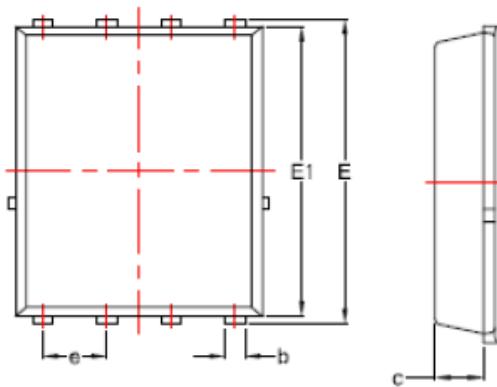


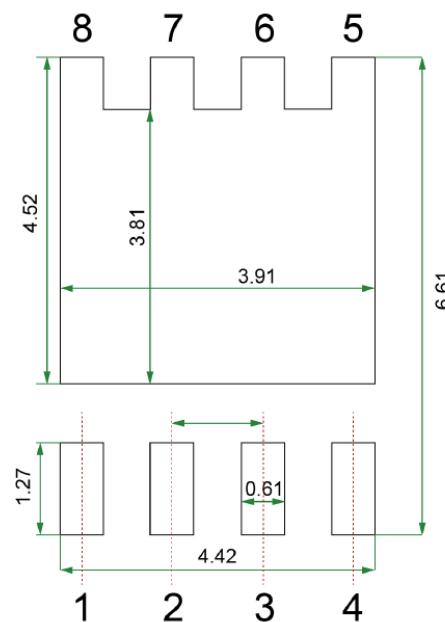
Fig.11 Unclamped Inductive Waveform

DFN5×6 Outline



Land Pattern (Only for Reference)
Unit : mm

SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.20	0.0354	0.0474
b	0.30	0.51	0.0118	0.0200
c	0.60	1.046	0.0236	0.0412
D	4.80	5.45	0.1890	0.2146
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.20	0.1890	0.2047
E	5.90	6.35	0.2323	0.2500
E1	5.65	6.06	0.2224	0.2386
E2	1.10	-	0.0433	-
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.61	0.0150	0.0240
L2	0.30	0.71	0.0118	0.0280
H	3.30	3.92	0.1300	0.1543
I	-	0.18	-	0.0070



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